

AW-XM632-PUR

**IEEE 802.11 a/b/g/n/ac/ax Wi-Fi 6E
+ Bluetooth 6.0 Combo Module**

Datasheet

Rev.C

DF

(For Standard)

Features

Wi-Fi

- 802.11a/b/g/n/ac/ax compliant, tri-band capable (2.4/5/6 GHz).
- 5/6 GHz: 20/40/80-MHz channels, 1024-QAM, 1x1 providing up to 600 Mbps PHY data rate.
- 2.4 GHz: 20/40[1]-MHz channels, 1024-QAM, 1x1 providing up to 287 Mbps PHY data rate.
- 802.11ax STA mode and Soft AP mode with 11ax scheduled access.
- Supports 802.11d, h, k, r, v, w, ai.
- On-chip power amplifiers and low-noise amplifiers.
- Supports multipoint external coexistence interface to optimize bandwidth utilization with other co-located wireless technologies such as LTE.
- Fast VSDB (Virtual Simultaneous Dual Band).
- Worldwide regulatory support: Global products supported with worldwide homologated design.
- Integrated Arm® Cortex® R4 processor with tightly coupled memory for complete WLAN subsystem functionality. This architecture offloads the host processor completely from WLAN functionality.
- Transmission and reception of HE-SU and HE-ER-SU PPDU.
- Reception of HE-MU PPDU-OFDMA/MU-MIMO Frame.
- Transmission of HE-TB PPDU (Uplink MU OFDMA).

Bluetooth

- Bluetooth 6.0 (BDR + EDR + BLE).
- All Bluetooth 5.0/5.1/5.2 optional features supported including LE-Audio.
- Supports ISOAL HCI Enhancement (6.0) to enhance low latency and high reliable audio.

- Dedicated Bluetooth® RF path for best Wi-Fi + Bluetooth coexistence performance.
- Bluetooth Class 1 or Class 2 transmitter operation.
- Supports extended synchronous connections (eSCO), for enhanced voice quality by allowing for retransmission of dropped packets.
- Adaptive frequency hopping (AFH) for reducing radio frequency interference.
- Interface support, host controller interface (HCI) using a high-speed UART interface and PCM/I2S for audio data.
- Supports multiple simultaneous Advanced Audio Distribution Profiles (A2DP) for stereo sound.
- On-chip memory includes 512 KB SRAM and 2 MB ROM.

Interface

- PCIe Gen2 (3.0 Compliant) for WLAN: complies with PCI Express base specification revision 3.0 for x1 lane and power management running at Gen2 speeds.
- HCI-UART, PCM/I2S for Bluetooth.

Coexistence

- Built-in advanced algorithms for Wi-Fi + Bluetooth coexistence.
- 2-wire SECI for external 3rd party Bluetooth®/GPS/LTE radios.

General

- Fully integrated programmable dynamic Power Management Unit.
- Supports 1.8 V VDDIO.



AzureWave

AzureWave Technologies, Inc.

- Supports 1340 Bytes of OTP shared between Bluetooth and WLAN for storing board parameters.



AzureWave Technologies, Inc.

Revision History

Document NO: R2-2632-DST-01

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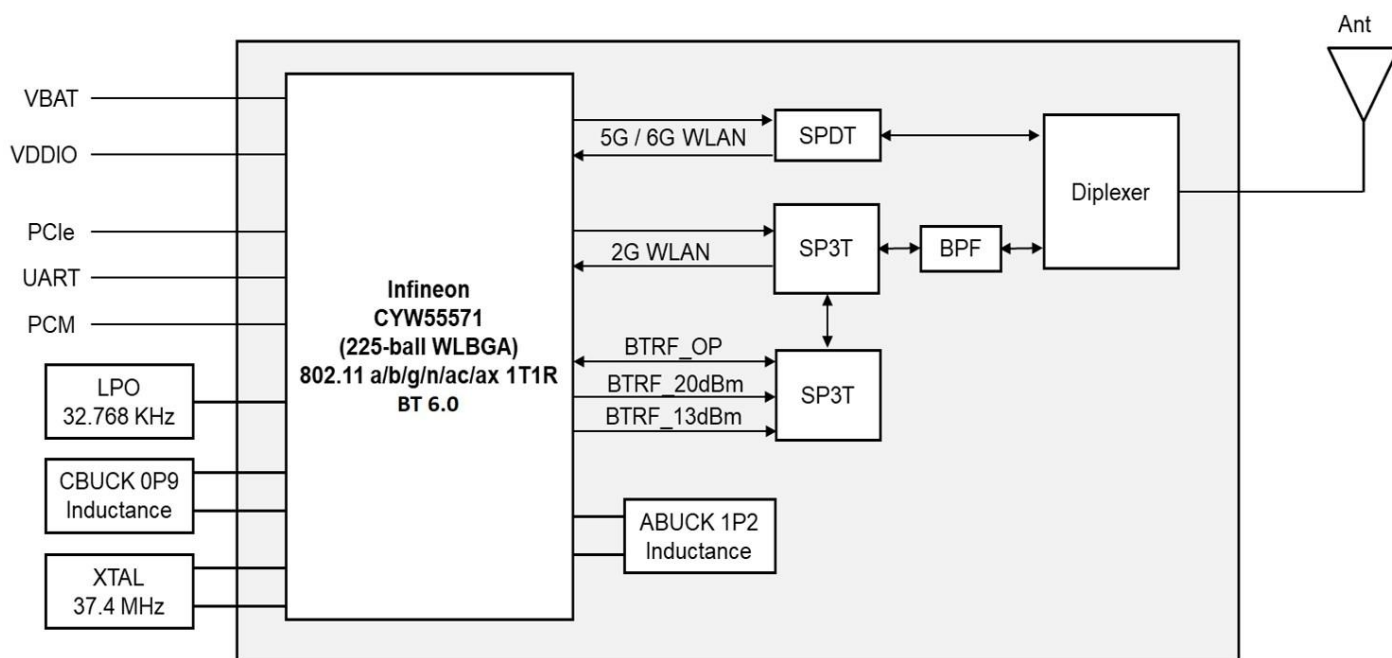
1. Introduction

1.1 Product Overview

The AW-XM632-PUR device provides the highest level of integration for commercial and Industrial IoT wireless systems with integrated tri-band 1x1 Wi-Fi 6E WLAN MAC/baseband/radio, Bluetooth 6.0 MAC/baseband/radio, and integrated Power Management Unit. WLAN and Bluetooth radios also include on-chip power amplifiers and low-noise amplifiers to further reduce the need for external components.

WLAN interfaces to host processor through a PCIe v3.0 Gen2 interface while Bluetooth host interface is provided through high-speed 4-wire UART interface. Additionally, the Bluetooth section supports PCM and I2S interfaces for audio applications. AW-XM632-PUR is qualified to operate across Industrial (−40°C to +85°C) temperature.

1.2 Block Diagram



AW-XM632-PUR Block Diagram

1.3 Specifications Table

1.3.1 General

Features	Description
Product Description	802.11 a/b/g/n/ac/ax Wi-Fi 6E + Bluetooth 6.0 Combo Module
Major Chipset	Infineon CYW55571 WLBGA
Host Interface	Wi-Fi + BT → PCIe + UART
Dimension	12 mm x 12 mm x 1.93 mm
Form factor	LGA, 49 pins
Antenna	Tri-band 1x1 ANT : Wi-Fi/Bluetooth → TX/RX
Weight	0.6 (g)

1.3.2 WLAN

Features	Description
WLAN Standard	IEEE 802.11 a/b/g/n/ac/ax
WLAN VID/PID	N/A
WLAN SVID/SPID	N/A
Frequency Range	WLAN: 2.4 / 5 / 6 GHz Band
Modulation	DSSS DBPSK(1Mbps), DQPSK(2Mbps), CCK(11/5.5Mbps) OFDM BPSK(9/6Mbps/MCS0), QPSK(18/12Mbps/MCS1~2), 16-QAM(36/24Mbps/MCS3~4), 64-QAM(72.2/54/48Mbps/MCS5~7), 256-QAM(MCS8~9), 1024-QAM(MCS10~11)
Number of Channels	2.4GHz <ul style="list-style-type: none"> ● USA, Canada and Taiwan – 1 ~ 11 ● China, Most European Countries – 1 ~ 13 ● Japan, 1 ~ 13 5GHz <ul style="list-style-type: none"> ● USA, EUROPE – 36, 40, 44, 48, 52, 56, 60, 64, 100, 104, 108, 112, 116, 120, 124, 128, 132, 136, 140, 149, 153, 157, 161, 165 6GHz <ul style="list-style-type: none"> ● CH1~CH233

Output Power¹ (Board Level Limit)**	2.4G				
		Min	Typ	Max	Unit
	11b (11Mbps) @EVM<35%	16	18	20	dBm
	11g (54Mbps) @EVM ≤ -25 dB	15	17	19	dBm
	11n (HT20 MCS7) @EVM ≤ -27 dB	14.5	16.5	18.5	dBm
	11ax (HE20 MCS11) @EVM ≤ -35 dB	12	14	16	dBm
	5G				
		Min	Typ	Max	Unit
	11a (54Mbps) @EVM<-25 dB	14	16	18	dBm
	11n (HT20 MCS7) @EVM ≤ -27 dB	14	16	18	dBm
	11n (HT40 MCS7) @EVM ≤ -27 dB	14	16	18	dBm
	11ac (VHT20 MCS8) @EVM ≤ -30 dB	13.5	15.5	17.5	dBm
	11ac (VHT40 MCS9) @EVM ≤ -32 dB	12.5	14.5	16.5	dBm
	11ac (VHT80 MCS9) @EVM ≤ -32 dB	12	14	16	dBm
	11ax (HE20 MCS11) @EVM ≤ -35 dB	12.5	14.5	16.5	dBm
	11ax (HE40 MCS11) @EVM ≤ -35 dB	12	14	16	dBm
	11ax (HE80 MCS11) @EVM ≤ -35 dB	11.5	13.5	15.5	dBm
	6G				
		Min	Typ	Max	Unit
	11ax (HE20 MCS11) @EVM ≤ -35 dB	10	12	14	dBm
	11ax (HE40 MCS11) @EVM ≤ -35 dB	9	11	13	dBm
	11ax (HE80 MCS11) @EVM ≤ -35 dB	8	10	12	dBm

¹ Unless otherwise stated, limit values apply for an ambient temperature of +25 °C.

Receiver Sensitivity**	2.4G				
		Min	Typ	Max	Unit
	11b (11Mbps)		88	85	dBm
	11g (54Mbps)		76	73	dBm
	11n (HT20 MCS7)		74	71	dBm
	11ax (HE20 MCS11)		63	60	dBm
	5G				
		Min	Typ	Max	Unit
	11a (54Mbps)		74	71	dBm
	11n (HT20 MCS7)		72	69	dBm
	11n (HT40 MCS7)		69	66	dBm
	11ac (VHT20 MCS8)		67	64	dBm
	11ac (VHT40 MCS9)		63	60	dBm
	11ac (VHT80 MCS9)		60	57	dBm
	11ax (HE20 MCS11)		60	57	dBm
	11ax (HE40 MCS11)		56	53	dBm
	11ax (HE80 MCS11)		55	52	dBm
	6G				
		Min	Typ	Max	Unit
	11ax (HE20 MCS11)		56	53	dBm
	11ax (HE40 MCS11)		54	51	dBm
	11ax (HE80 MCS11)		52	49	dBm
Data Rate	802.11b: 1, 2, 5.5, 11Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54Mbps 802.11n: MCS0~7 HT20/HT40 802.11a: 6, 9, 12, 18, 24, 36, 48, 54Mbps 802.11ac: MCS0~8 VHT20 802.11ac: MCS0~9 VHT40/VHT80 802.11ax: MCS10~11 HE20/HE40/HE80				
Security	<ul style="list-style-type: none"> ● WEP ● WPA/WPA2/WPA3 Enterprise with 192-bit encryption ● WMM, WMM-PS (U-APSD), WMM-SA ● AES (hardware accelerator), ● TKIP (hardware accelerator) ● CKIP (software support) 				

* If you have any certification questions about output power please contact FAE directly

**Tx power variation ± 3.0 dB for process, voltage and temperature variation across -40°C to $+85^{\circ}\text{C}$.

1.3.3 Bluetooth

Features	Description				
Bluetooth Standard	Bluetooth 6.0				
Bluetooth VID/PID	N/A				
Frequency Range	2400~2483.5MHz				
Modulation	GFSK (1Mbps), $\pi/4$ DQPSK (2Mbps) and 8DPSK (3Mbps)				
Output Power*		Min	Typ	Max	Unit
	BDR	3	6	9	dBm
	Low Energy (2MHz)	3	6	9	dBm
Receiver Sensitivity**		Min	Typ	Max	Unit
	BDR		-90	-87	dBm
	EDR		-86	-83	dBm
	Low Energy (2MHz)		-92	-89	dBm

* If you have any certification questions about output power please contact FAE directly

** Project is in engineering stage, RF performance is still being verified.

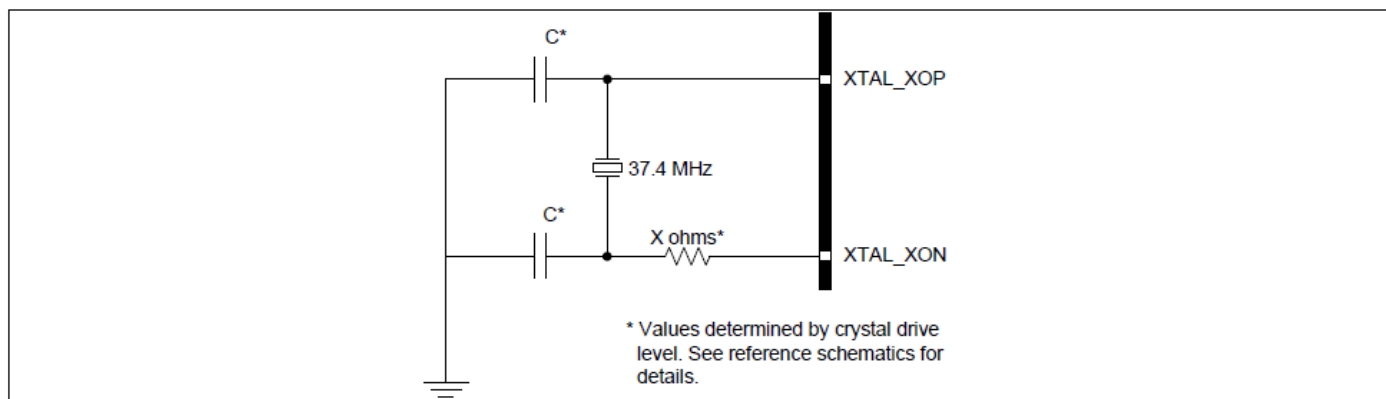
1.3.4 Operating Conditions

Features	Description
Operating Conditions	
Voltage	3.3V
Operating Temperature	-40°C to 85°C
Operating Humidity	less than 85% R.H.
Storage Temperature	-40°C to 125°C
Storage Humidity	less than 60% R.H.
ESD Protection	
Human Body Model	1000V
Changed Device Model	250V

1.4 Frequency references

1.4.1 XTAL requirements and performance

AW-XM632-PUR can use an external crystal to provide a frequency reference. The recommended configuration for the crystal oscillator including all external components. Consult the reference schematics for the latest configuration.



A fractional-N synthesizer in AW-XM632-PUR generates radio frequencies, clocks, and data/packet timing, enabling it to operate using a wide selection of frequency references.

The recommended default frequency reference is a 37.4 MHz crystal. The signal characteristics for the crystal oscillator interface are listed in Table.

Parameter	Conditions/Notes	Crystal ¹			Unit
		Min	Typ	Max	
Frequency	2.4G, 5G, and 6G bands: IEEE 802.11ac/ax operation	-	37.4	-	MHz
Frequency tolerance over the lifetime of the equipment, including temperature ²	Without trimming	-20.0	-	20.0	ppm
Crystal load capacitance	-	-	12.0	-	pF
ESR	-	-	-	60.0	Ω
Drive level	External crystal must be able to tolerate this drive level.	200	-	-	μW
Input impedance XTAL_XOP	Resistive	-	-	-	k Ω
	Capacitive	-	-	7.5	pF

Notes:

1. Use XTAL_XOP and XTAL_XON.
2. It is the responsibility of the equipment designer to select oscillator components that comply with these specifications.

1.4.2 External 32.768 kHz sleep clock specifications

AW-XM632-PUR requires an external low-frequency clock for low-power mode timing. An external 32.768 kHz precision oscillator which meets the requirements listed must be used.

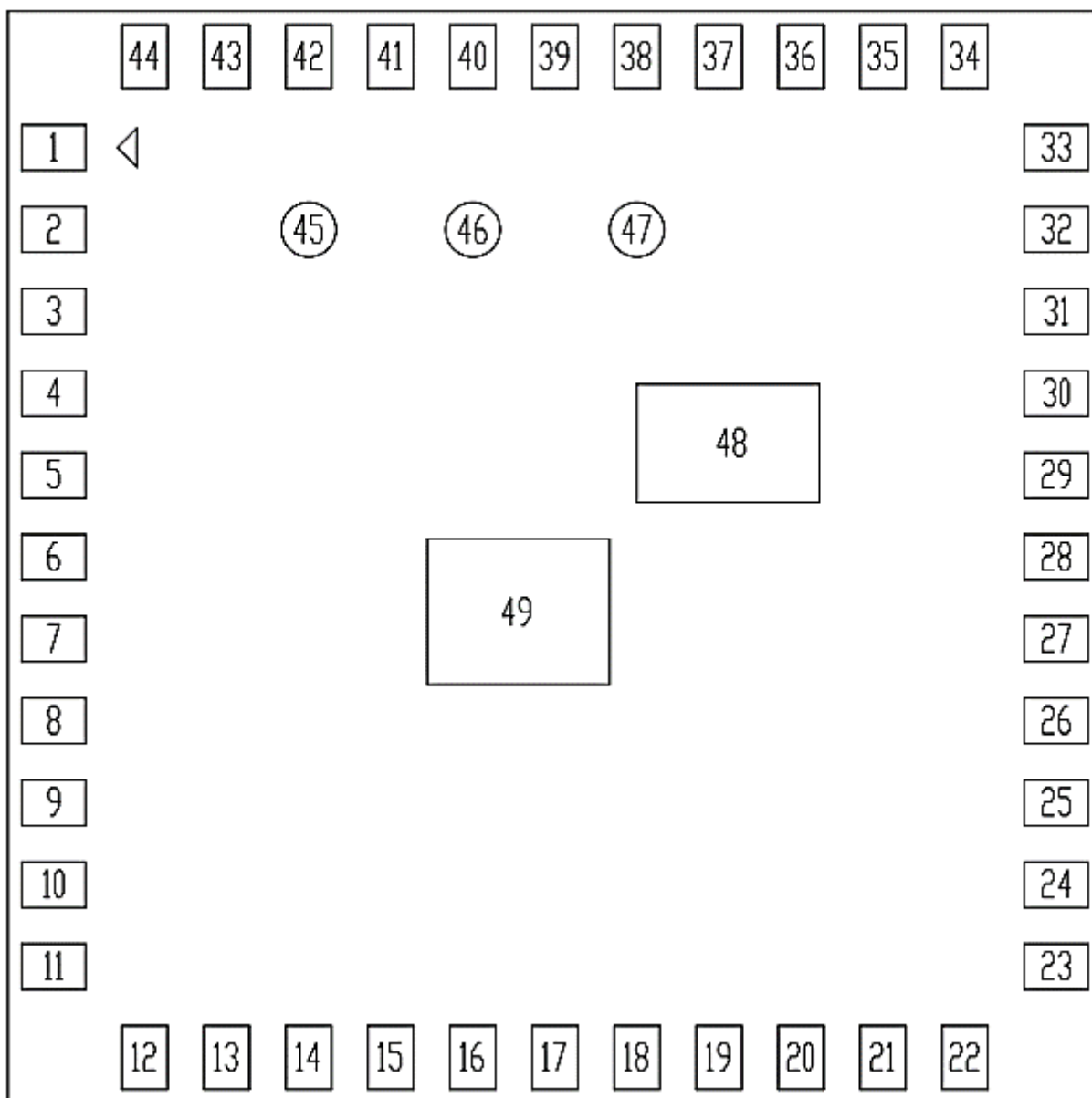
Parameter	LPO clock	Unit
Nominal input frequency	32.768	kHz
Frequency accuracy	±250	ppm
Duty cycle	30 – 70	%
Input signal amplitude	200–1800	mV, p–p
Signal type	Square-wave or sine-wave	-
Input impedance ¹	> 100k	Ω
Clock jitter ² (during initial startup)	< 5	pF
	< 10,000	ppm

Notes:

1. When power is applied or switched off.
2. The LPO_IN input receiver has ac-coupled capacitance on the input with the feedback resistor to maintain the common mode around VDDIO/2 and power supply noise should be maintained less than 100mV to avoid any false glitches before the time constant (ac- coupled capacitance * feedback resistor, i.e., 100 μs) settles down.

2. Pin Definition

2.1 Pin Map



AW-XM632-PUR Pin Map (Top View)

2.2 Pin Table

Pin No	Definition	Basic Description	Voltage	Type
1	GND	Ground.	-	GND
2	NC	Floating		-
3	GND	Ground.	-	GND
4	GND	Ground.	-	GND
5	ANT	WLAN/BT RF ANT.		RF
6	GND	Ground.	-	GND
7	GND	Ground.	-	GND
8	BT_PCM_OUT	PCM data output.	VDDIO	O
9	BT_PCM_CLK	PCM clock; can be master (output) or slave (input).	VDDIO	I/O
10	BT_PCM_IN	PCM data input.	VDDIO	I
11	BT_PCM_SYNC	PCM sync, can be master (output) or slave (input).	VDDIO	I/O
12	BT_UART_CTS_N	UART clear-to-send. Active-low clear-to-send signal for the HCI UART interface.	VDDIO	I
13	BT_UART_RXD	UART serial input. Serial data input for the HCI UART interface.	VDDIO	I
14	BT_UART_TXD	UART Serial Output. Serial data output for the HCI UART interface.	VDDIO	O
15	BT_UART_RTS_N	UART request-to-send. Active-low request-to-send signal for the HCI UART interface. BT LED control pin.	VDDIO	O
16	BT_DEV_WAKE	Bluetooth DEVICE WAKE.	VDDIO	I/O
17	BT_REG_ON	Used by the PMU to power up or power down the internal regulators used by the Bluetooth® section. When deasserted, this pin holds the Bluetooth section in reset. This pin has an internal 50 kΩ pull-down resistor that is auto enabled/disabled by programming.	VDDIO	I
18	GND	Ground.	-	GND
19	WL_HOST_WAKE	WLAN HOST_WAKE.	VDDIO	I/O
20	VBAT	3.3V power pin.	3.3V	PWR
21	GND	Ground.	-	GND
22	CSR_VLX	CSR Power Stage Output to Inductor.	0.9V	O

23	CBUCK_0P9	Internal Buck 0.9V voltage generation pin.	0.9V	I
24	GND	Ground.	-	GND
25	PCIE_TDP	PCIE Transmitter Differential Pair Positive Output.	-	O
26	PCIE_TDN	PCIE Transmitter Differential Pair Negative Output.	-	O
27	GND	Ground.	-	GND
28	PCIE_RDP	PCIE Receiver Differential Pair Negative Input.	-	I
29	PCIE_RDN	PCIE Receiver Differential Pair Positive Input.		I
30	GND	Ground.	-	GND
31	PCIE_REFCLKN	PCI Express differential clock input Negative.	-	I
32	PCIE_REFCLKP	PCI Express differential clock input Positive.	-	I
33	GND	Ground.	-	GND
34	LPO_IN	External Low Power Clock input (32.768KHz).	-	I
35	GND	Ground.	-	GND
36	XTAL_OUT	External Xtal Output (37.4MHz).		O
37	XTAL_IN	External Oscillator Input. (37.4MHz).	-	I
38	GND	Ground.	-	GND
39	BT_HOST_WAKE	Bluetooth HOST WAKE.	-	I/O
40	PCIE_CLKREQ_L	PCIe clock request signal which indicates when the REFCLK to the PCIe interface can be gated. 1 = the clock can be gated. 0 = the clock is required.	-	OD
41	PCIE_PME_L	PCI power management event output. Used to request a change in the device or system power state. The assertion and deassertion of this signal is asynchronous to the PCIe reference clock. This signal has an open-drain output structure, as per the PCI Bus Local Bus Specification, revision 2.3.	-	OD
42	PCIE_PREST_L	PCIe System Reset. This input is the PCIe reset as defined in the PCIe base specification v1.1	-	I
43	VDDIO	1.8 V IO Supply for WLAN GPIOs.	1.8V	PWR
44	WL_REG_ON	Used by the PMU to power up or power down the internal AW-XM632-PUR regulators used by the WLAN section. When deasserted, this pin holds the WLAN section in	VDDIO	I

		reset. This pin has an internal 50 KΩ pull-down resistor that is auto enabled/disabled by programming.		
45	GPIO_2	GPIO configuration pin	VDDIO	I/O
46	GPIO_3	GPIO configuration pin	VDDIO	I/O
47	GPIO_4	GPIO configuration pin	VDDIO	I/O
48	GND	Ground.	-	GND
49	GND	Ground.	-	GND

3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VBAT	DC supply for the VBAT and PA driver supply	-0.5	-	6.0	V
VDDIO	DC supply voltage for digital I/O	-0.5	-	2.2	V
T_j	Maximum junction temperature	-	-	125	°C

3.2 Recommended Operating Conditions

Symbol	Parameter	Minimum	Typical	Maximum	Unit
VBAT	Power supply for Internal Regulator	3.13	3.3	3.47	V
VDDIO	DC supply voltage for digital I/O	1.71	1.8	1.89	V

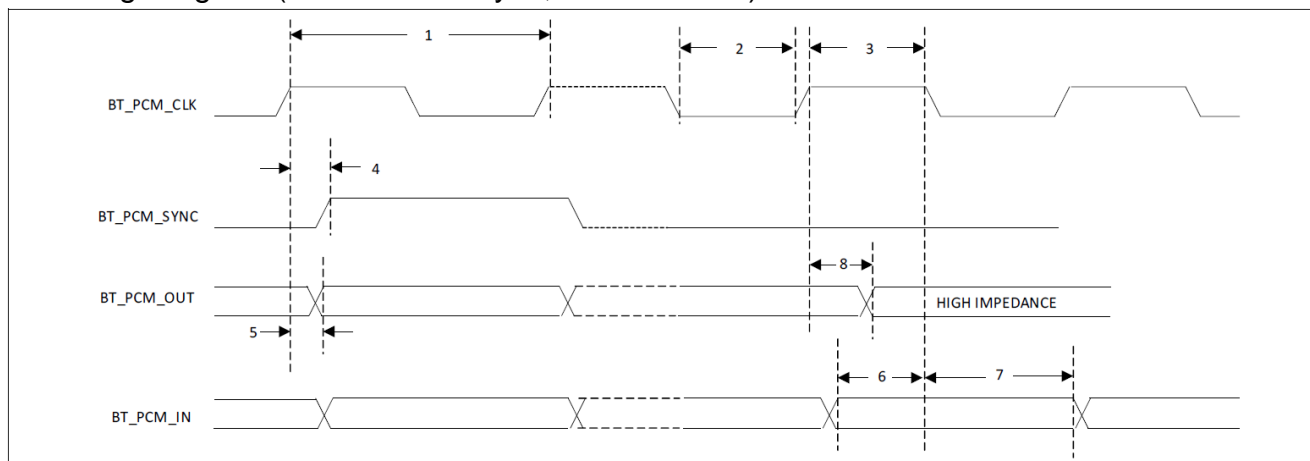
3.3 Digital IO Pin DC Characteristics

Symbol	Parameter	Minimum	Typical	Maximum	Unit
Digital I/O pins, VDDIO=1.8V					
V_{IH}	Input high voltage	0.65 × VDDIO	-	-	V
V_{IL}	Input low voltage	-	-	0.35 × VDDIO	V
V_{OH}	Output high voltage	VDDIO – 0.40	-	-	V
V_{OL}	Output Low Voltage	-	-	0.45	V
WL_REG_ON & BT_REG_ON Pins					
-	Input high voltage	1.2	-	VBAT	-
-	Input low voltage	-	-	0.3	-

3.4 Host Interface

3.4.1 PCM Interface Timing

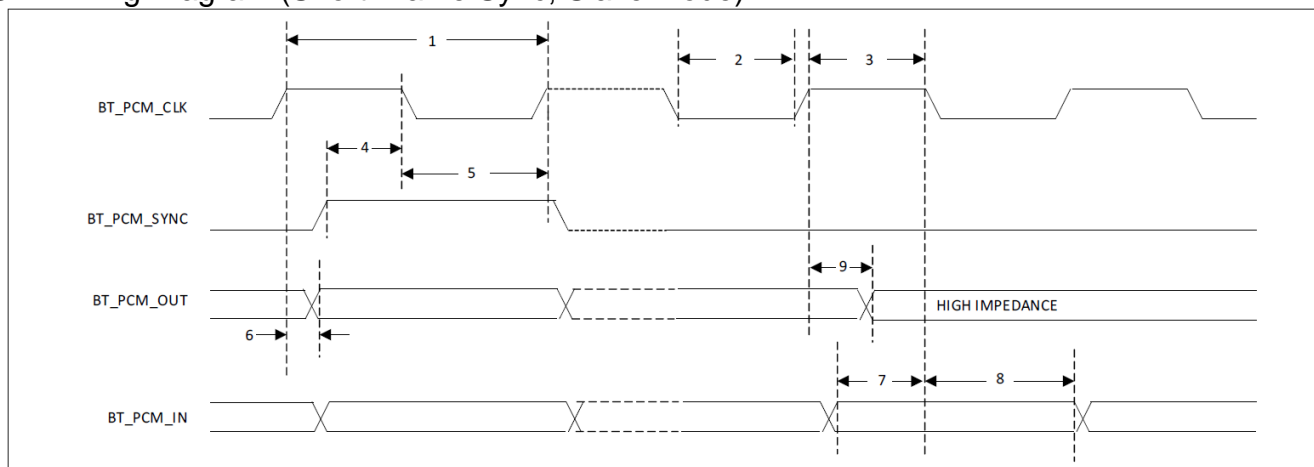
PCM Timing Diagram (Short Frame Sync, Master Mode)



PCM Interface Timing Specifications (Short Frame Sync, Master Mode)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock LOW	41	—	—	ns
3	PCM bit clock HIGH	41	—	—	ns
4	PCM_SYNC delay	0	—	25	ns
5	PCM_OUT delay	0	—	25	ns
6	PCM_IN setup	8	—	—	ns
7	PCM_IN hold	8	—	—	ns
8	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	—	25	ns

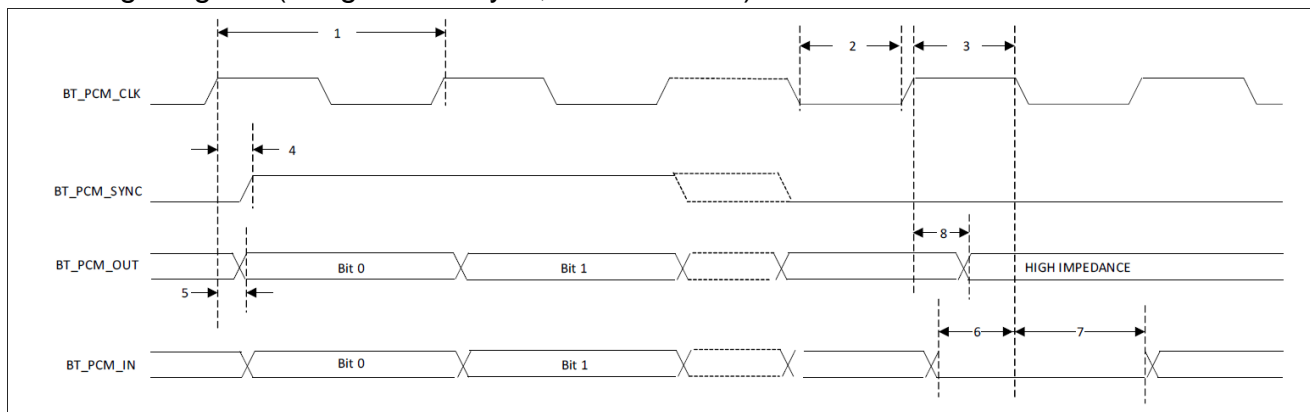
PCM Timing Diagram (Short Frame Sync, Slave Mode)



PCM Interface Timing Specifications (Short Frame Sync, Slave Mode)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock LOW	41	—	—	ns
3	PCM bit clock HIGH	41	—	—	ns
4	PCM_SYNC setup	8	—	—	ns
5	PCM_SYNC hold	8	—	—	ns
6	PCM_OUT delay	0	—	25	ns
7	PCM_IN setup	8	—	—	ns
8	PCM_IN hold	8	—	—	ns
9	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0		25	ns

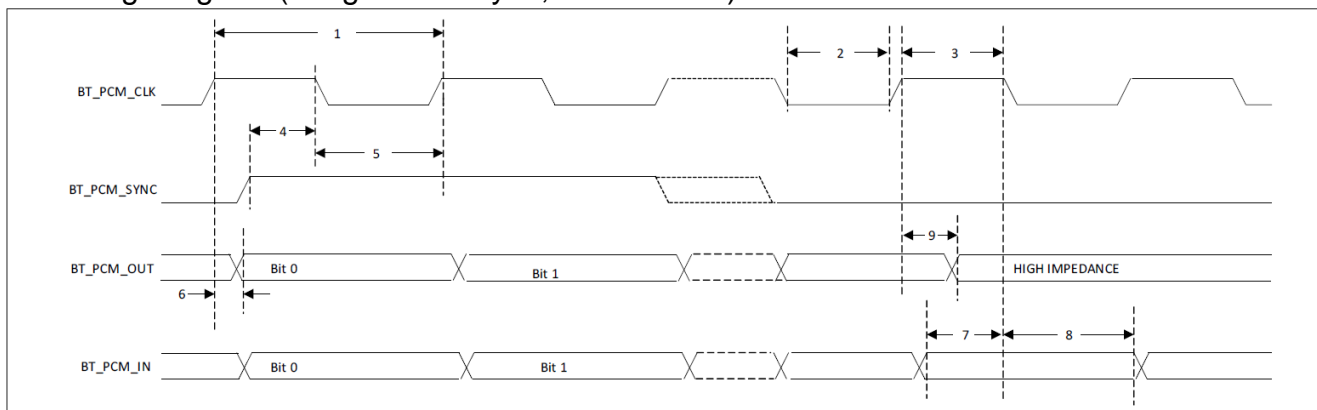
PCM Timing Diagram (Long Frame Sync, Master Mode)



PCM Interface Timing Specifications (Long Frame Sync, Master Mode)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock LOW	41	—	—	ns
3	PCM bit clock HIGH	41	—	—	ns
4	PCM_SYNC delay	0	—	25	ns
5	PCM_OUT delay	0	—	25	ns
6	PCM_IN setup	8	—	—	ns
7	PCM_IN hold	8	—	—	ns
8	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	—	25	ns

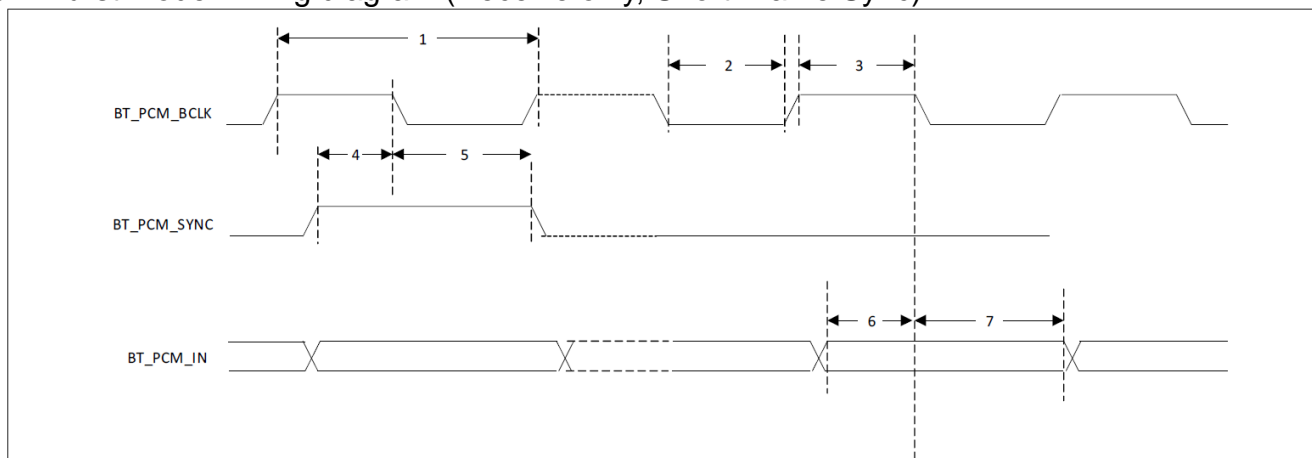
PCM Timing Diagram (Long Frame Sync, Slave Mode)



PCM Interface Timing Specifications (Long Frame Sync, Slave Mode)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	12	MHz
2	PCM bit clock LOW	41	—	—	ns
3	PCM bit clock HIGH	41	—	—	ns
4	PCM_SYNC setup	8	—	—	ns
5	PCM_SYNC hold	8	—	—	ns
6	PCM_OUT delay	0	—	25	ns
7	PCM_IN setup	8	—	—	ns
8	PCM_IN hold	8	—	—	ns
9	Delay from rising edge of PCM_BCLK during last bit period to PCM_OUT becoming high impedance	0	—	25	ns

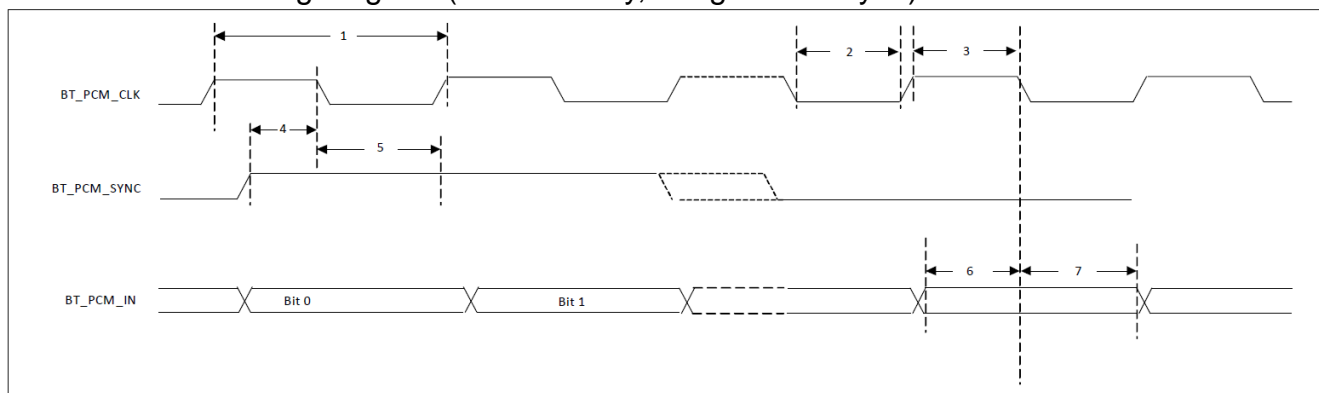
PCM Burst Mode Timing diagram (Receive only, Short Frame Sync)



PCM Burst Mode (Receive Only, Short Frame Sync)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	24	MHz
2	PCM bit clock LOW	20.8	—	—	ns
3	PCM bit clock HIGH	20.8	—	—	ns
4	PCM_SYNC setup	8	—	—	ns
5	PCM_SYNC hold	8	—	—	ns
6	PCM_IN setup	8	—	—	ns
7	PCM_IN hold	8	—	—	ns

PCM Burst Mode Timing diagram (Receive only, Long Frame Sync)



PCM Burst Mode (Receive Only, Long Frame Sync)

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	PCM bit clock frequency	—	—	24	MHz
2	PCM bit clock LOW	20.8	—	—	ns
3	PCM bit clock HIGH	20.8	—	—	ns
4	PCM_SYNC setup	8	—	—	ns
5	PCM_SYNC hold	8	—	—	ns
6	PCM_IN setup	8	—	—	ns
7	PCM_IN hold	8	—	—	ns

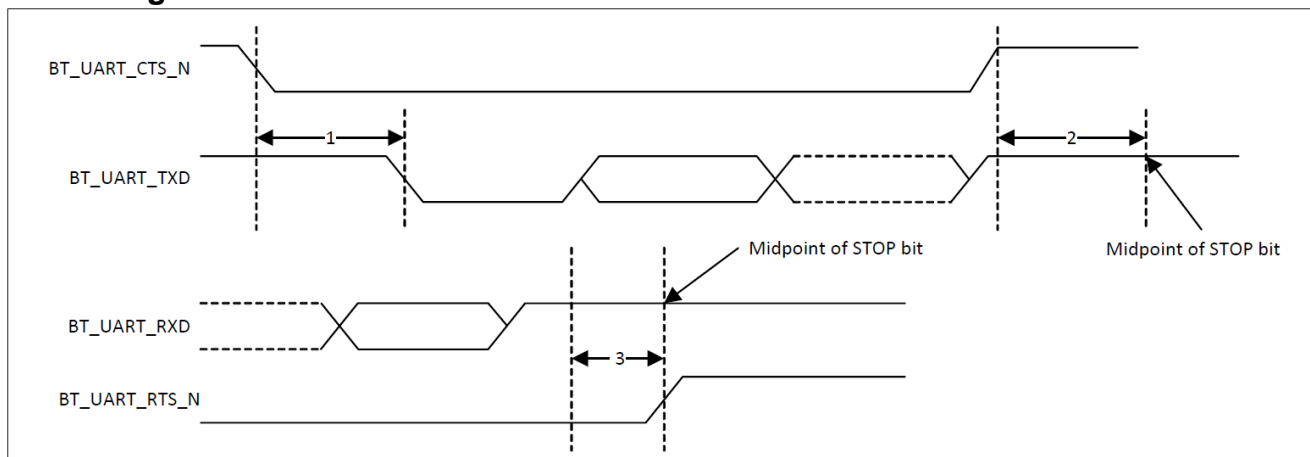
3.4.2 UART Interface

The AW-XM632-PUR UART is a standard 4-wire interface (RX, TX, RTS, and CTS) with adjustable baud rates from 9600 bps to 4.0 Mbps. The baud rate may be selected through a vendor-specific UART HCI command. UART has a 1040-byte receive FIFO and a 1040-byte transmit FIFO to support EDR. Access to the FIFOs is conducted through the AHB interface through either DMA/CPU. The UART supports the Bluetooth 6.0 UART HCI specification. The default baud rate is 115.2 Kbaud.

The AW-XM632-PUR UART can perform XON/XOFF flow control and includes hardware support for the Serial Line Input Protocol (SLIP). It can also perform wake-on activity. For example, activity on the RX or CTS inputs can wake the chip from a sleep state.

Normally, the UART baud rate is set by a configuration record downloaded after device reset and the host does not need to adjust the baud rate. Support for changing the baud rate during normal HCI UART operation is included through a vendor-specific command that allows the host to adjust the contents of the baud rate registers. The AW-XM632-PUR UARTs operate correctly with the host UART as long as the combined baud rate error of the two devices is within $\pm 2\%$.

UART Timing



UART Timing specifications

Reference	Characteristics	Minimum	Typical	Maximum	Unit
1	Delay time, BT_UART_CTS_N low to BT_UART_TXD valid	—	—	1.5	Bit periods
2	Setup time, BT_UART_CTS_N high before midpoint of stop bit	—	—	0.5	Bit periods
3	Delay time, midpoint of stop bit to BT_UART_RTS_N high	—	—	0.5	Bit periods

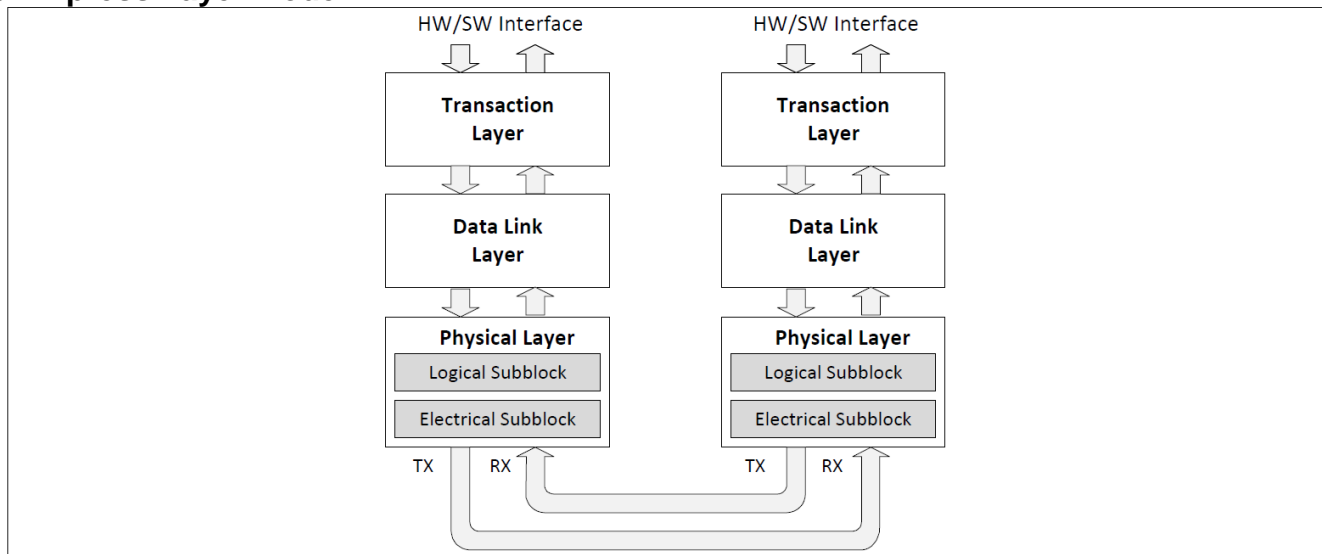
3.4.3 PCI Express Interface

The PCI Express (PCIe) core on the AW-XM632-PUR is a high-performance serial I/O interconnect that is protocol compliant and electrically compatible with the PCI Express Base Specification v3.0. This core contains all the necessary blocks, including logical and electrical functional sub-blocks to perform PCIe functionality and maintain high-speed links, using existing PCI system configuration software implementations without modification.

Organization of the PCIe core is in logical layers: Transaction Layer, Data Link Layer, and Physical Layer, as shown in Figure. A configuration or link management block is provided for enumerating the PCIe configuration space and supporting generation and reception of System Management Messages by communicating with PCIe layers.

Each layer is partitioned into dedicated transmit and receive units that allow point-to-point communication between the host and AW-XM632-PUR device. The transmit side processes outbound packets while the receive side processes inbound packets. Packets are formed and generated in the Transaction and Data Link Layer for transmission onto the high-speed links and onto the receiving device. A header is added at the beginning to indicate the packet type and any other optional fields.

PCI Express Layer Model



3.5 Power up Timing Sequence

AW-XM632-PUR has two signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN, and internal regulator blocks. These signals are described below. Additionally, diagrams are provided to indicate proper sequencing of the signals for various operational states. The timing values indicated are minimum required values; longer delays are also acceptable.

3.5.1 Description of Control Signals

■ **WL_REG_ON**: Used by the PMU to power up the WLAN section. It is also OR-gated with the BT_REG_ON input to control the internal AW-XM632-PUR regulators. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low the WLAN section is in reset. If both the BT_REG_ON and WL_REG_ON pins are low, the regulators are disabled.

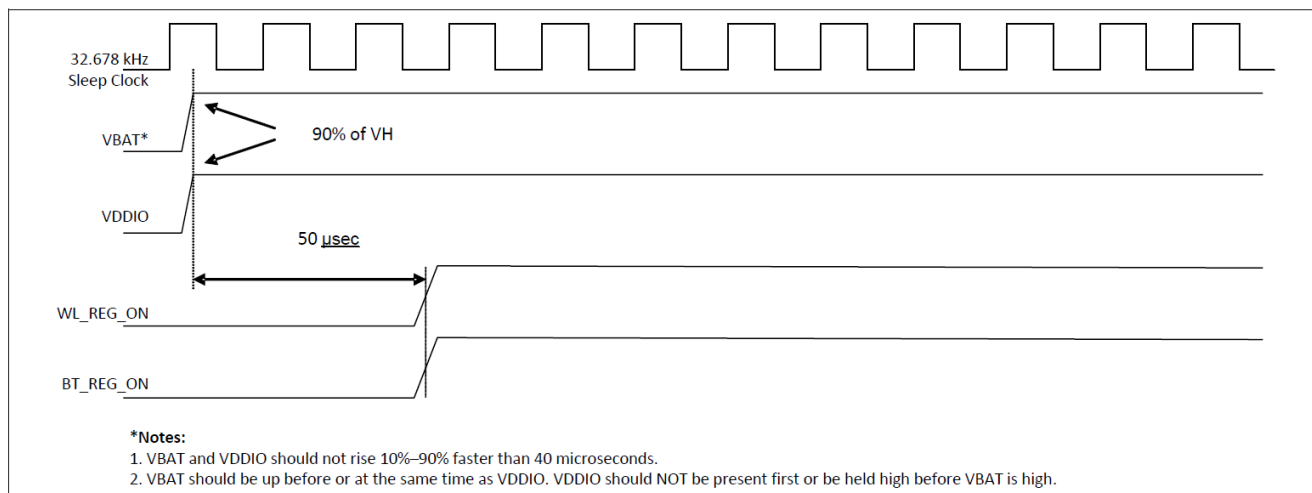
■ **BT_REG_ON**: Used by the PMU (OR-gated with WL_REG_ON) to power up the internal AW-XM632-PUR regulators. If both the BT_REG_ON and WL_REG_ON pins are low, the regulators are disabled. When this pin is low and WL_REG_ON is high, the Bluetooth section is in reset.

■ **Note**

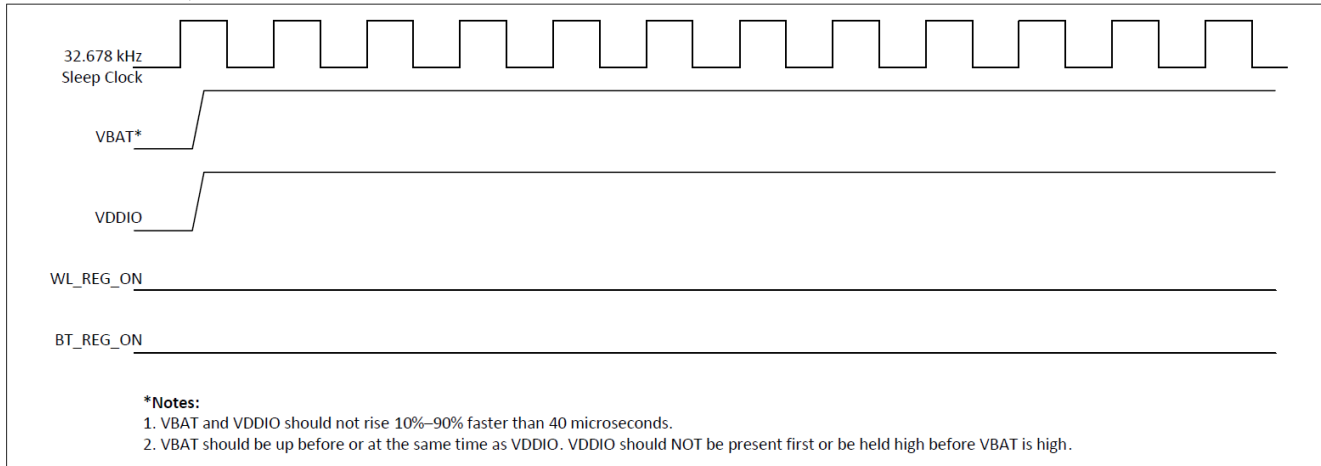
VBAT and VDDIO should not rise 10%–90% faster than 40 microseconds.

3.5.2 Control Signal Timing Diagrams

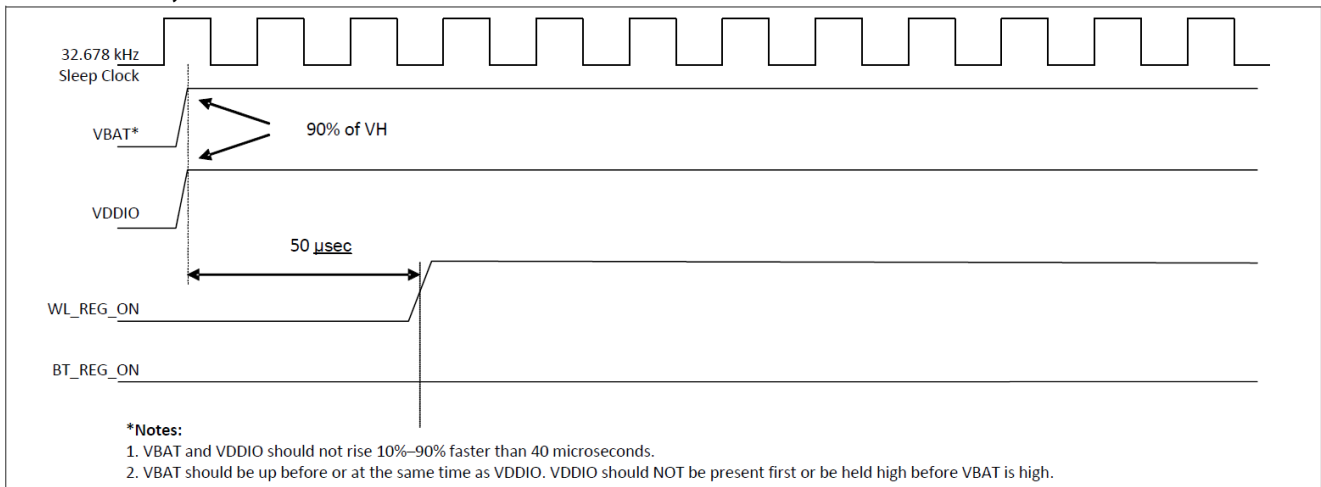
■ **WLAN = ON, Bluetooth = ON**



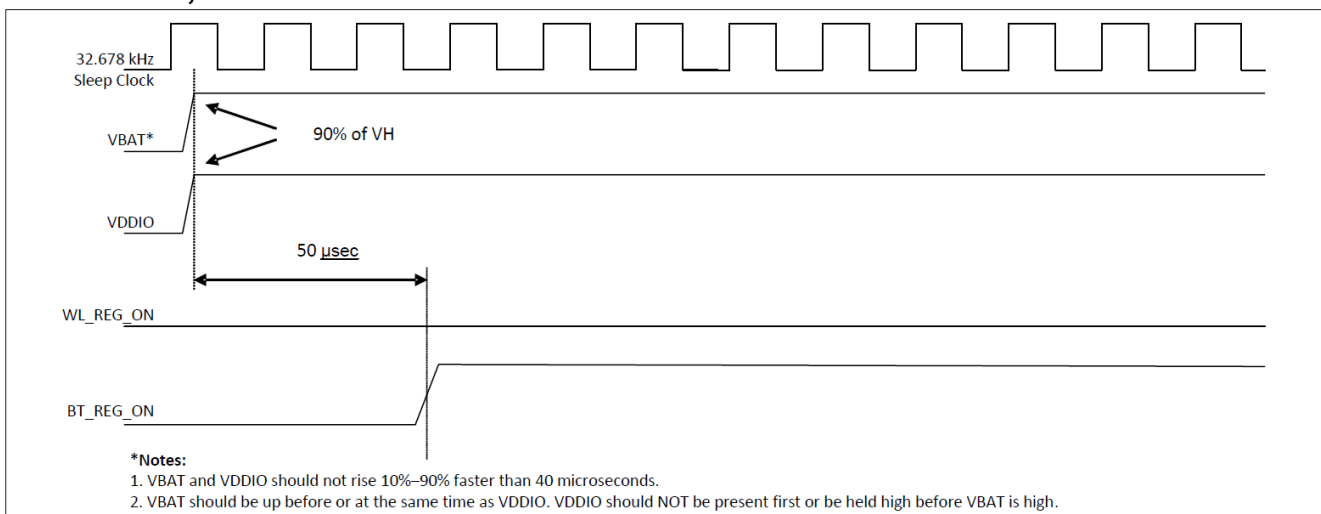
■ WLAN = OFF, Bluetooth = OFF



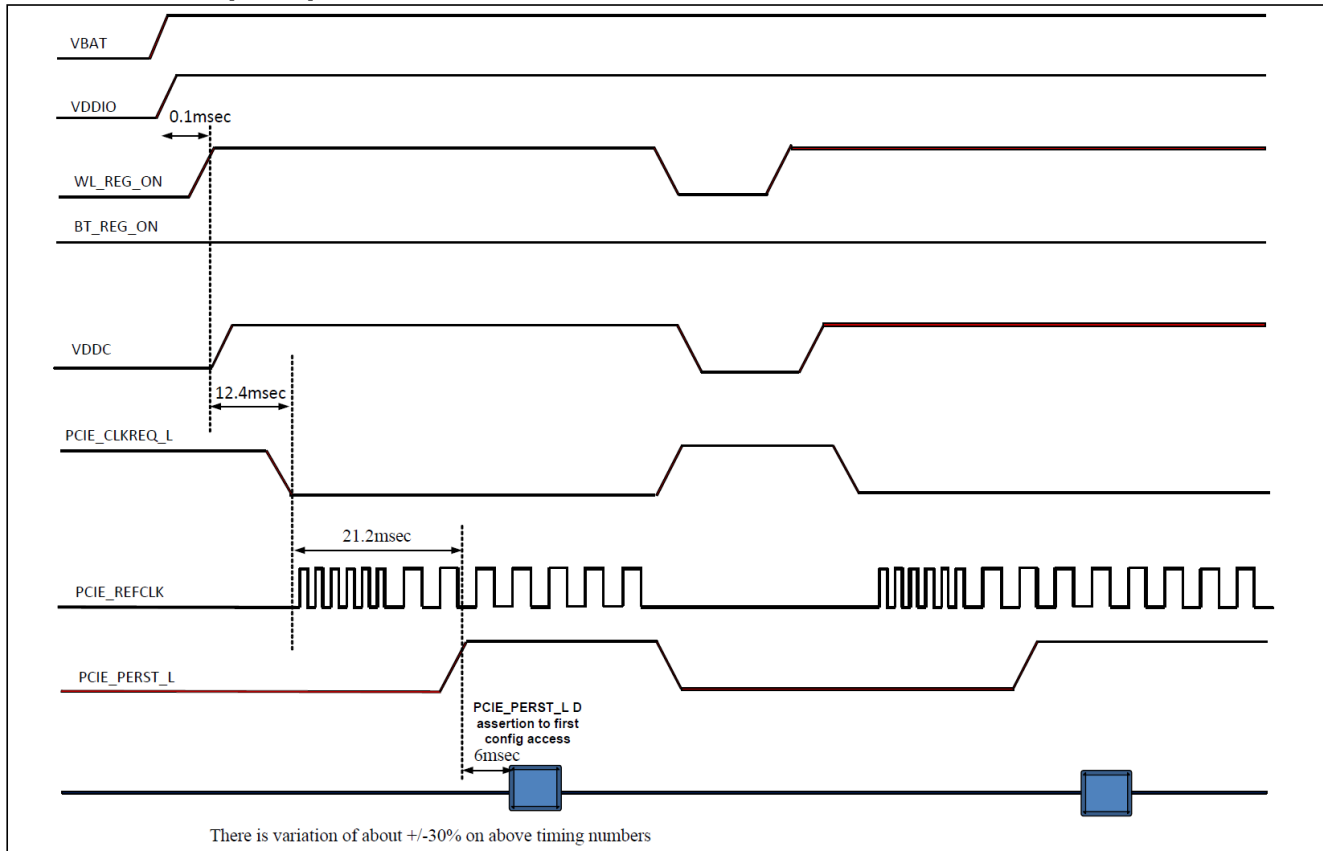
■ WLAN = ON, Bluetooth = OFF



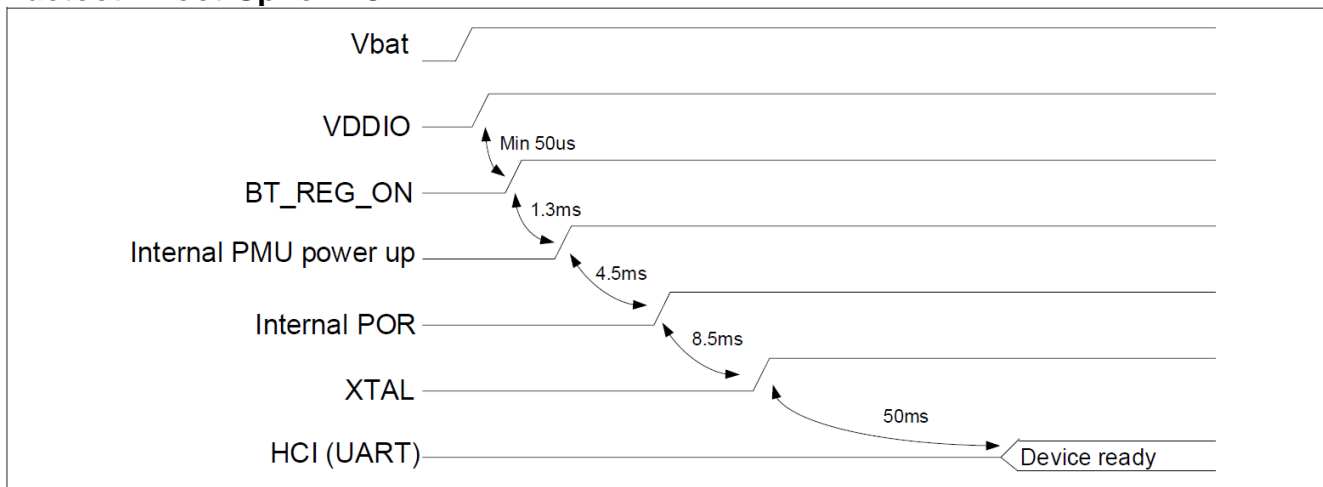
■ WLAN = OFF, Bluetooth = ON



■ WLAN Power-Up Sequence for PCIe Host



■ Bluetooth Boot-Up for HCI



3.6 Power Consumption*

3.6.1 WLAN

No.	Item			VBAT_IN=3.3 V	
				Max.	Avg.
1	Pdn ^{*(1) (2) (5)}			0.02	0.0002
2	Deep Sleep ^{*(2) (3) (5) (7)} (Not associated with AP)			57.3	8.8
3	Power Save DTIM 1 (2.4GHz) ^{*(2) (4)(5) (7)}			28.7	8.6
4	Power Save DTIM 1 (5GHz) ^{*(2) (4)(5) (7)}			25.1	8.5
5	Power Save DTIM 1 (6GHz) ^{*(2) (4)(5) (6) (7)}			85.2	9.6
Band (GHz)	Mode	BW (MHz)	RF Power (dBm)	Transmit ^{*(7)}	
				Max.	Avg.
2.4	11b@11Mbps	20	18	303	285
	11g@54Mbps	20	17	276	194
	11n@MCS7	20	16.5	276	186
	11ax@MCS0 NSS1	20	14	250	215
	11ax@MCS11 NSS1	20	14	254	165
5	11a@6Mbps	20	16	362	310
	11n@MCS7	40	16	379	220
	11ac@MCS0 NSS1	80	14	370	295
	11ac@MCS9 NSS1	80	14	363	215
	11ax@MCS0 NSS1	80	13.5	373	287
	11ax@MCS11 NSS1	80	13.5	364	212
6	11ax@MCS0 NSS1	20	12	310	268
	11ax@MCS11 NSS1	20	12	309	196
	11ax@MCS0 NSS1	40	11	310	254
	11ax@MCS11 NSS1	40	11	305	182
	11ax@MCS0 NSS1	80	10	305	236
	11ax@MCS11 NSS1	80	10	304	187
Band (GHz)	Mode	BW(MHz)		Receive ^{*(7)}	
				Max.	Avg.
2.4	11b@11Mbps	20		71	68
	11n@MCS7	20		75	71
	11ax@MCS11 NSS1	20		76	70
5	11a@54Mbps	20		80	76
	11n@MCS7	40		90	84
	11ac@MCS9 NSS1	80		102	95
	11ax@MCS11 NSS1	80		109	94
6	11ax@MCS11 NSS1	20		83	77
	11ax@MCS11 NSS1	40		95	84
	11ax@MCS11 NSS1	80		109	93

*Current Unit: mA

No.	Item			VDDIO=1.8 V	
				Max.	Avg.
1	Pdn ^{*(1) (2) (5)}			0.014	0.00048
2	Deep Sleep ^{*(2) (3) (5) (7)} (Not associated with AP)			1.2	1.2
3	Power Save DTIM 1 (2.4GHz) ^{*(2) (4)(5) (7)}			1.3	1.2
4	Power Save DTIM 1 (5GHz) ^{*(2) (4)(5) (7)}			1.3	1.2
5	Power Save DTIM 1 (6GHz) ^{*(2) (4)(5) (6) (7)}			1.3	1.2
Band (GHz)	Mode	BW (MHz)	RF Power (dBm)	Transmit ^{*(7)}	
				Max.	Avg.
2.4	11b@1Mbps	20	18	5.3	5.1
	11ax@MCS11 NSS1	20	14	5.3	5.2
5	11a@6Mbps	20	16	5.3	5.0
	11ax@MCS11 NSS1	80	13.5	5.3	5.2
6	11ax@MCS11 NSS1	80	10	5.3	5.2
Band (GHz)	Mode	BW(MHz)		Receive ^{*(7)}	
				Max.	Avg.
2.4	11b@11Mbps	20		1.3	1.2
5	11ax@MCS11 NSS1	80		1.3	1.2
6	11ax@MCS11 NSS1	80		1.3	1.2

*Current Unit: mA

3.6.2 Bluetooth

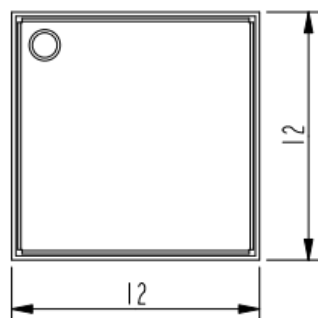
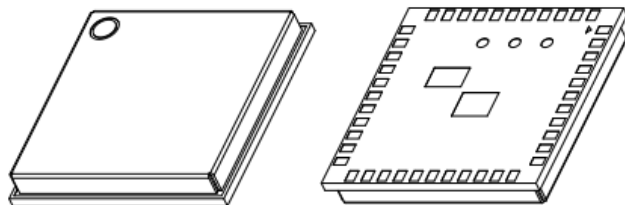
Mode	Packet Type	RF Power (dBm)	VBAT_IN=3.3 V	
			Max.	Avg.
Sleep ^{*(1)}	N/A	N/A	0.457	0.036
Transmit ^{*(1) (2)}	DH5	6	24	16
Receive ^{*(1) (2)}	DH5	N/A	24	13

*Current Unit: mA

Mode	Packet Type	RF Power (dBm)	VDDIO=1.8 V	
			Max.	Avg.
Sleep ^{*(1)}	N/A	N/A	22.6	13.0
Transmit ^{*(1) (2)}	DH5	6	313	281
Receive ^{*(1) (2)}	DH5	N/A	311	277

*Current Unit: mA

4.1 Mechanical Drawing



TOLERANCE UNLESS OTHERWISE SPECIFIED: ± 0.1 mm

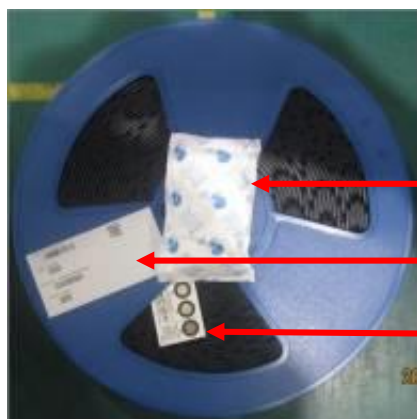
5. Packaging Information

1. One reel can pack 1,500pcs 12x12 stamp/LGA modules

(整軸產品數量為 1500pcs)

2. One production label is pasted on the reel, one desiccant and one humidity indicator card are put on the reel

(卷軸貼上一張生產標籤，並放上一包防潮包及濕度指示卡)



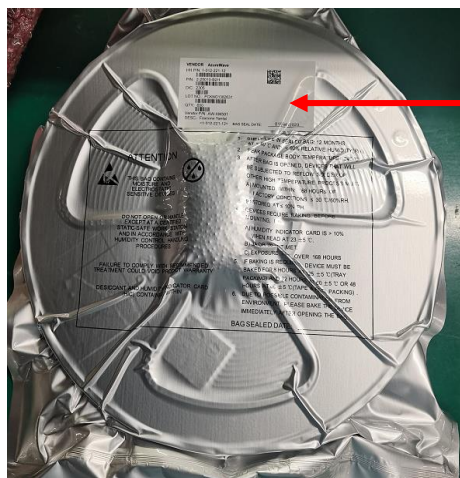
One desiccant

One production label

One humidity indicator card

3. One reel is put into the anti-static moisture barrier bag, and then one production label is pasted on the bag

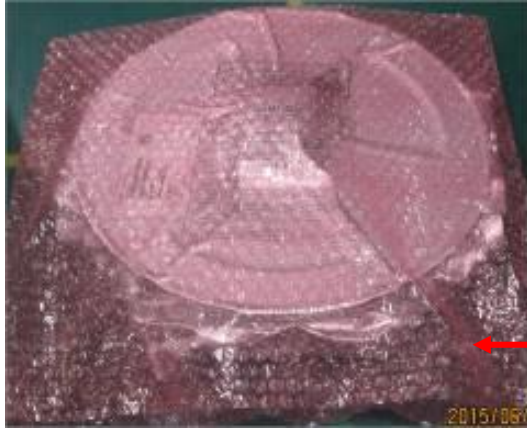
(卷軸放進防靜電鋁箔袋，再貼上一張生產標籤)



One production label
生產標籤

4. A bag is put into the anti-static pink bubble wrap

(防靜電鋁箔袋放進氣泡袋內)



One anti-static pink bubble wrap

5. A bubble wrap is put into the inner box and then one label is pasted on the inner box
(氣泡袋放進內箱中，再貼上一張生產標籤)



One production label

6. **5 inner boxes** could be put into one carton
(五個內箱可以放進一個外箱)



Production

7. Sealing the carton by transparent tape

(使用透明膠帶將外箱進行工字型封箱)



8. One carton label and one box label are pasted on the carton. If one carton is not full, one balance label pasted on the carton

(外箱上貼附出貨標籤和箱號標籤；如不滿箱，需貼附尾數標籤)

One carton label
出貨標籤



One box label
箱號標籤

